

ABSTRACT

A method for fabricating semiconductor components such
5 as printed circuit boards, multi chip modules, chip scale
packages, and test carriers is provided. The method includes
providing a substrate having a blanket deposited conductive
layer thereon. Using a laser machining process, grooves are
10 formed in the conductive layer to define patterns of
conductors on the substrate. The conductors can be formed
with a desired size and spacing, and can include features
such as bond pads, conductive vias, and external ball
contacts. In addition, selected conductors can be configured
15 as co-planar ground or voltage traces, for adjusting
impedance values in other conductors configured as signal
traces.

09420036-101899